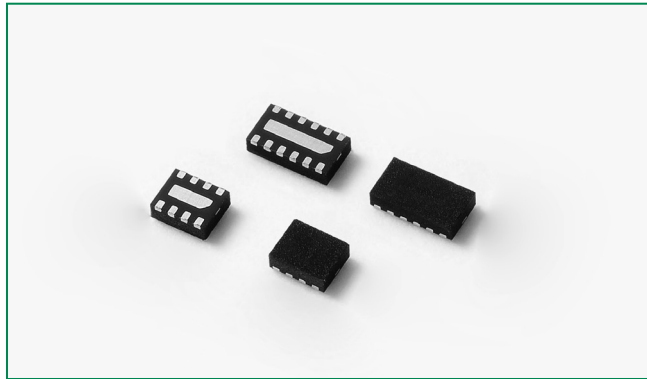


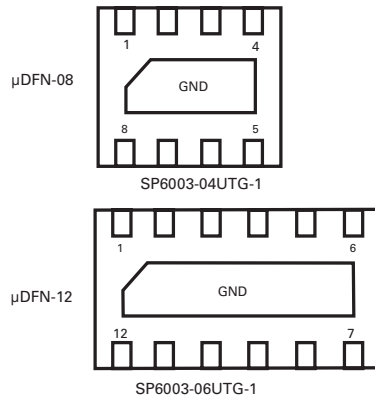
SP6003 Series 7pF EMI Filter Array with ESD Protection



Description

Littelfuse's SP6003 integrates 4 and 6 EMI filters (C-R-C) into a small, low-profile μ DFN package with each filter providing greater than -20dB attenuation at 1GHz. Additionally, each I/O is capable of shunting ± 12 kV ESD strikes (IEC61000-4-2, contact discharge) away from sensitive electronic components. The performance of this small, slim design makes it extremely suitable for mobile handsets, PDA's, and notebook computers.

Pinout



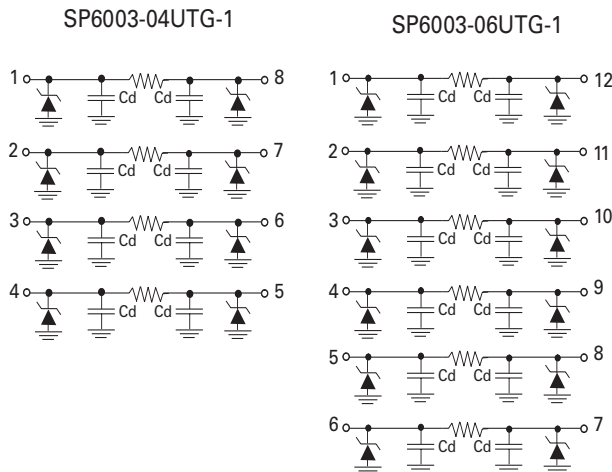
Features

- EMI filtering of frequencies from 800MHz to 3GHz
- Greater than -20dB attenuation (TYP) at 1GHz
- ESD, IEC61000-4-2, ± 12 kV contact, ± 15 kV air
- Small, low-profile μ DFN (JEDEC MO-229) package (TYP 0.5mm height)

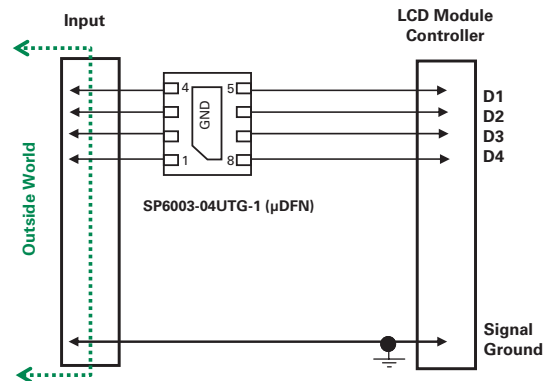
Applications

- Keypad Interface for Portable Electronics
- LCD and Camera Display Interfaces for Handsets
- Connector Interfaces for Handsets
- PDA's
- Digital Cameras
- Notebook Computers

Functional Block Diagram



Application Example



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
T _{OP}	Operating Temperature	-40 to 125	°C
T _{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 10s)	260	°C

Electrical Characteristics (T_{OP}=25°C)

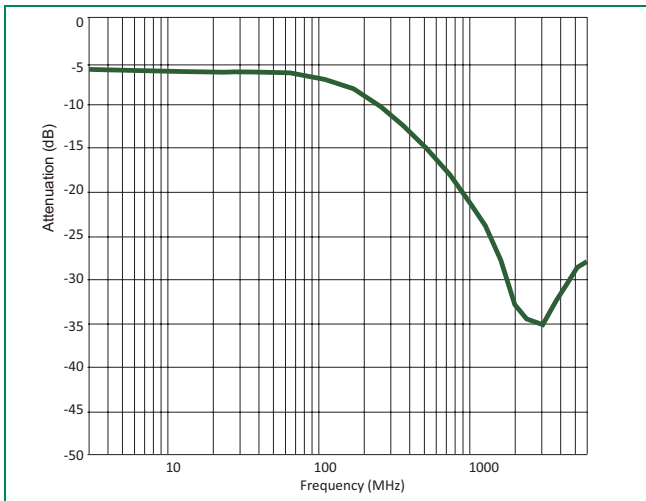
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V _{RWM}				5.0	V
Breakdown Voltage	V _{BR}	I _R =1mA		7.0		V
Reverse Leakage Current	I _{LEAK}	V _{RWM} =5V		0.1	1.0	µA
Resistance	R _A	I _R =10mA	80	100	120	Ω
Diode Capacitance ^{1,2}	C _D	V _R =2.5V, f=1MHz		7		pF
Line Capacitance ^{1,2}	C _L	V _R =2.5V, f=1MHz	11	14	17	pF
ESD Withstand Voltage ¹	V _{ESD}	IEC61000-4-2 (Contact Discharge)	±12			kV
		IEC61000-4-2 (Air Discharge)	±15			kV
Cutoff Frequency ³	F _{-3dB}	Above this frequency, appreciable attenuation occurs		250		MHz

Notes: ¹ Parameter is guaranteed by design and/or device characterization.

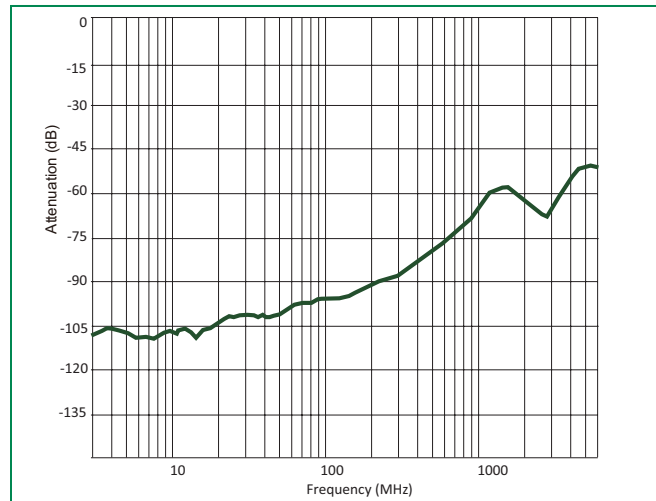
² Total line capacitance is two times the diode capacitance (C_D).

³ 50Ω source and 50Ω load termination

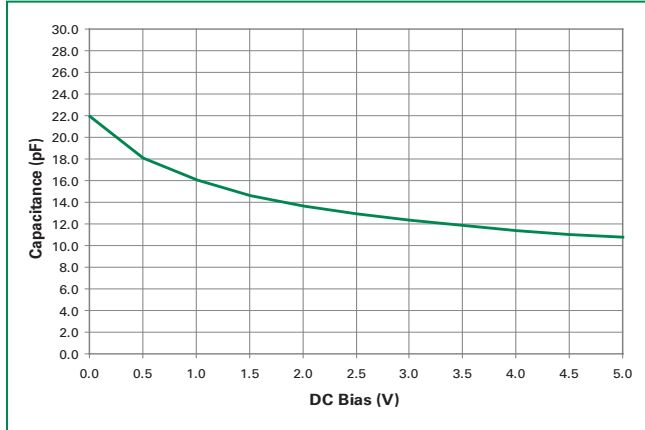
Insertion Loss (S21)



Analog Crosstalk (S41)



Line Capacitance vs. DC Bias



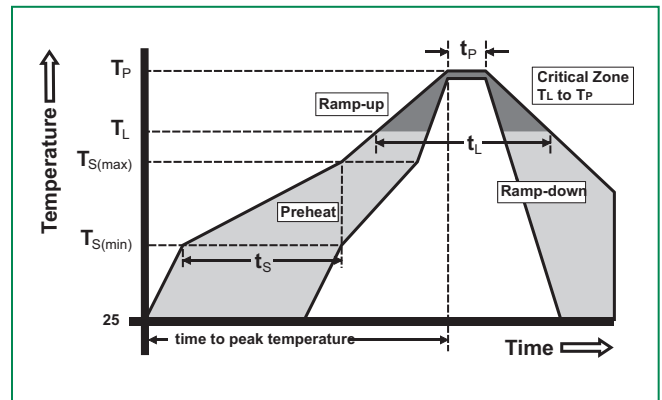
Product Characteristics

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

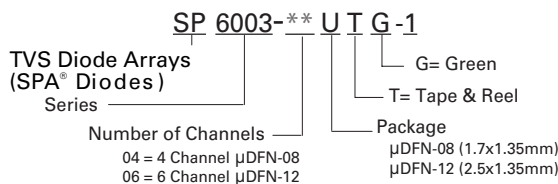
- Notes :
1. All dimensions are in millimeters
 2. Dimensions include solder plating.
 3. Dimensions are exclusive of mold flash & metal burr.
 4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
 5. Package surface matte finish VDI 11-13.

Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



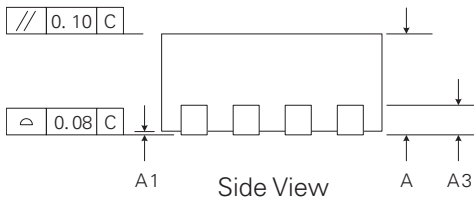
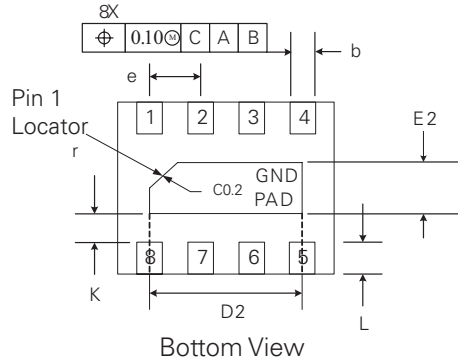
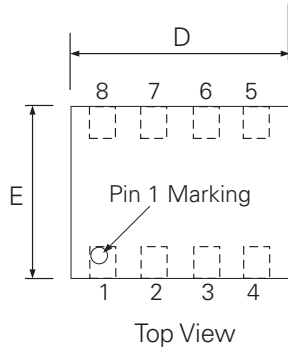
Part Numbering System



Ordering Information

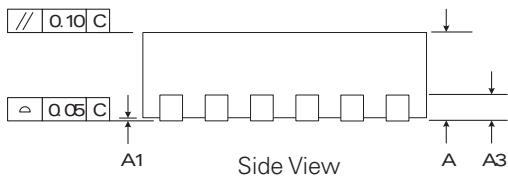
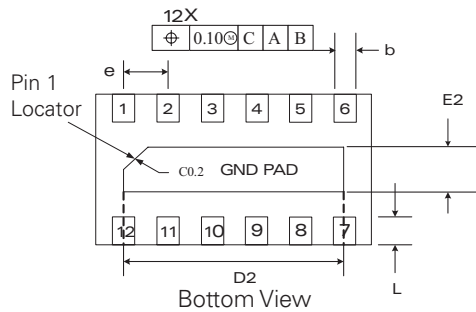
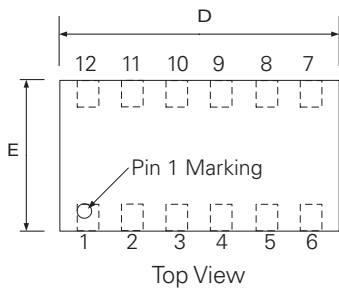
Part Number	Package	Size	Marking	Min. Order Qty.
SP6003-04UTG-1	μ DFN-08	1.7x1.35mm	C114	3000
SP6003-06UTG-1	μ DFN-12	2.5x1.35mm	C116YVWW	3000

Package Dimensions — μ DFN-08



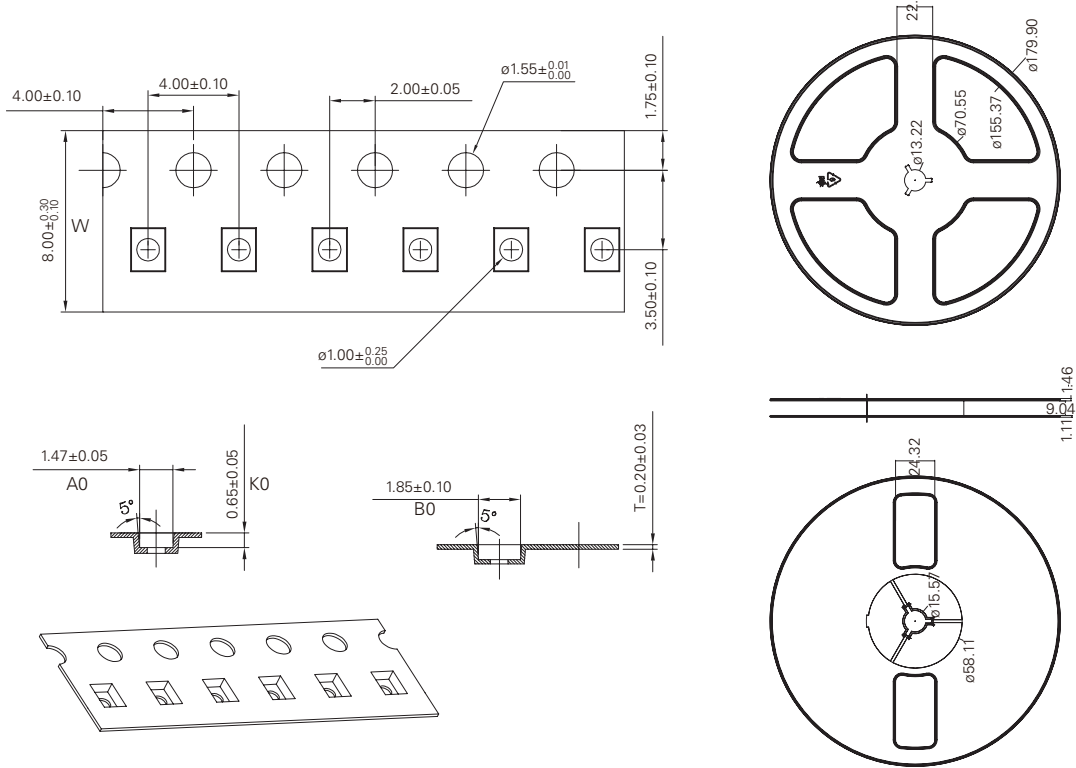
	μ DFN-08			
	JEDEC MO-229			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.45	0.55	0.018	0.022
A1	0.00	0.05	0.000	0.002
A3	0.152 REF		0.006 REF	
b	0.15	0.25	0.006	0.010
D	1.60	1.80	0.063	0.071
D2	1.10	1.30	0.043	0.051
E	1.25	1.45	0.049	0.057
E2	0.30	0.50	0.012	0.020
e	0.400 BSC		0.016 BSC	
K	0.20		0.008	
L	0.15	0.35	0.006	0.014

Package Dimensions — μ DFN-12



	μ DFN-12			
	JEDEC MO-229			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.45	0.55	0.018	0.022
A1	0.00	0.05	0.000	0.002
A3	0.102 REF		0.004 REF	
b	0.15	0.25	0.006	0.010
D	2.40	2.60	0.095	0.103
D2	1.90	2.10	0.075	0.083
E	1.25	1.45	0.050	0.058
E2	0.30	0.50	0.012	0.020
e	0.400 BSC		0.016 BSC	
L	0.15	0.35	0.006	0.014

Embossed Carrier Tape & Reel Specification — μ DFN-08



SP6003

Embossed Carrier Tape & Reel Specification — μ DFN-12

